Applications
- Radio Frequency Front End (RFFE)
- Filters
- Antennas
- Switches in mobile phones
- Medical equipment
- MEMS-based devices
- Interposers and semiconductor packaging substrates

Benefits
- Ability to lower electronic loss particularly at high frequency levels
- Capability to deliver glass as thin as 100µm
- Superior surface quality enables fine-line spacing

Precision Vias
<p>| | |</p>
<table>
<thead>
<tr>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>Wafer Size</td>
<td>100/150/200/300mm</td>
</tr>
<tr>
<td></td>
<td>100µm – 500µm in thickness</td>
</tr>
<tr>
<td>Panel Size</td>
<td>Up to 500mm x 500mm</td>
</tr>
<tr>
<td>Positional Accuracy</td>
<td>&lt;+- 10µm</td>
</tr>
<tr>
<td>Pitch</td>
<td>Minimum 2X via diameter</td>
</tr>
<tr>
<td>Via Diameter</td>
<td>30µm – 100µm</td>
</tr>
</tbody>
</table>

Commercial Readiness
- Now shipping commercial quantities of glass wafers with vias
- Multiple approaches and partners for via metallization
- World-class metrology enabling ultra-flat wafers with high positional accuracy of vias

Dielectric Loss
Glass vs. Silicon

Insertion loss measurement in collaboration with ITRI
Through Glass Via Solutions
Glass with precision vias ideal for RF components such as filters, switches, and antennas, and non-RF applications that require low-loss materials such as semiconductor interposers and packaging substrates.

Corning offers industry-leading wafer and panel format glass-based solutions. Our products help customers deliver increasingly demanding functionality and form factor requirements in consumer devices and Internet of Things applications.